



PRODUCT BULLETIN # 20592

Generic Copy

Issue Date: 30-Jul-2014

TITLE: Datasheet update to reflect current case outline for SIDAC axial package

EFFECTIVE DATE: 30-Oct-2014

AFFECTED CHANGE CATEGORY(S): Datasheet

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or <norsahida.sahman@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

The purpose of this Product Bulletin is to reflect the datasheet with current case outline for SIDAC axial package. There will be NO Change to any materials, processes, or physical dimensions in the manufacturing of the package.

This is only a change to specifications dimensional methodology of the case outline following JEDEC standard. This updating of the package case outline does not affect the form/fit/function of devices as no changes to products are occurring.

Old vs new case outline

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.370	0.380	9.40	9.65
B	0.190	0.210	4.83	5.33
D	0.048	0.052	1.22	1.32
K	1.000	—	25.40	—

Old Case Outline

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.287	0.374	7.30	9.50
B	0.189	0.209	4.80	5.30
D	0.047	0.051	1.20	1.30
K	1.000	---	25.40	---

Latest Case Outline

Please note that there is a significant different in the A dimension. This is due to utilize & follow the established JEDEC standard in the industry to ensure our products conform to these standards for the purpose of supply chain interchangeability.



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List of affected General Parts:

MKP3V120G
MKP3V120RLG
MKP3V240G
MKP3V240RLG